

# 2SK2114

## Silicon N Channel MOS FET

REJ03G0998-0200

(Previous: ADE-208-1346)

Rev.2.00 Sep 07, 2005

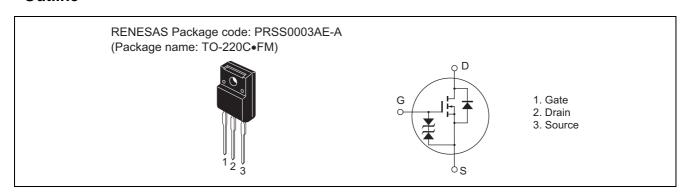
### **Application**

High speed power switching

#### **Features**

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for Switching regulator

#### **Outline**



# **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

| Item                                      | Symbol                   | Ratings     | Unit |
|---|--------------------------|-------------|------|
| Drain to source voltage                   | V <sub>DSS</sub>         | 450         | V    |
| Gate to source voltage                    | V <sub>GSS</sub>         | ±30         | V    |
| Drain current                             | I <sub>D</sub>           | 5           | Α    |
| Drain peak current                        | I <sub>D(pulse)</sub> *1 | 20          | А    |
| Body to drain diode reverse drain current | I <sub>DR</sub>          | 5           | Α    |
| Channel dissipation                       | Pch*2                    | 35          | W    |
| Channel temperature                       | Tch                      | 150         | °C   |
| Storage temperature                       | Tstg                     | -55 to +150 | °C   |

Notes: 1. PW  $\leq$  10  $\mu$ s, duty cycle  $\leq$  1 %

2. Value at Tc = 25°C

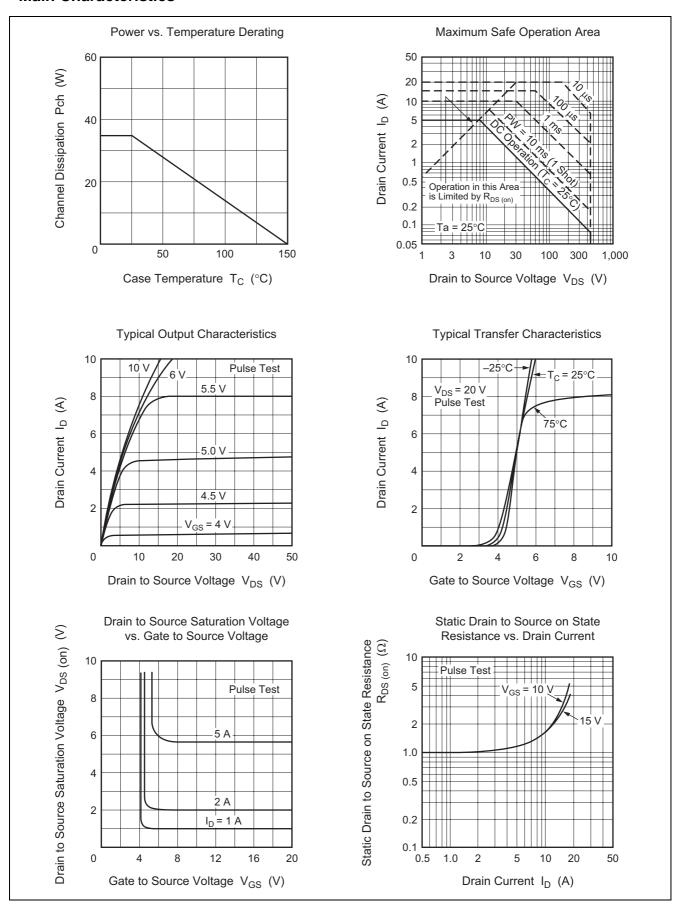
### **Electrical Characteristics**

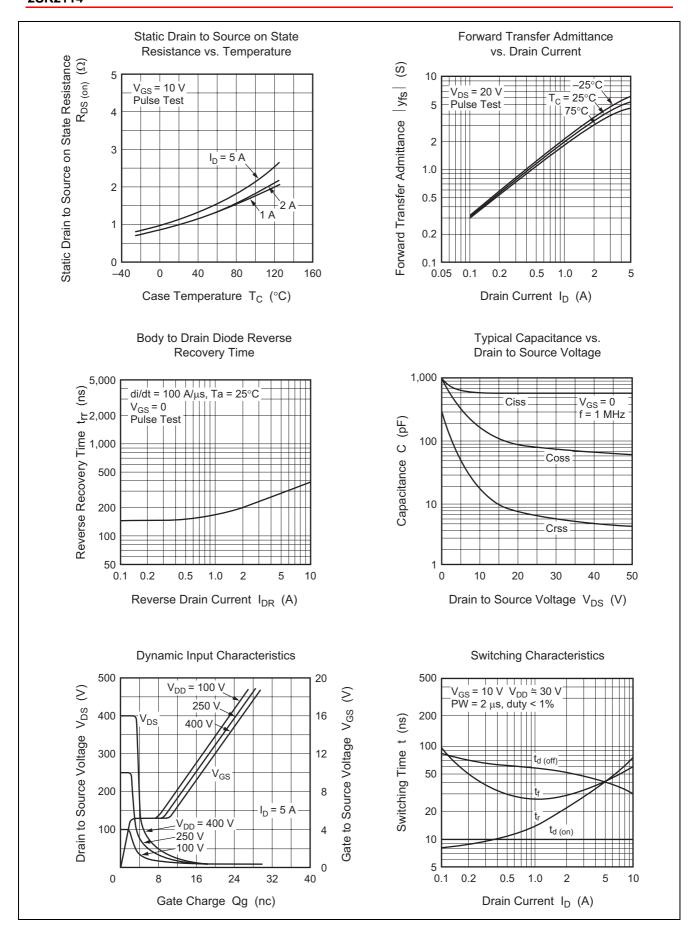
 $(Ta = 25^{\circ}C)$ 

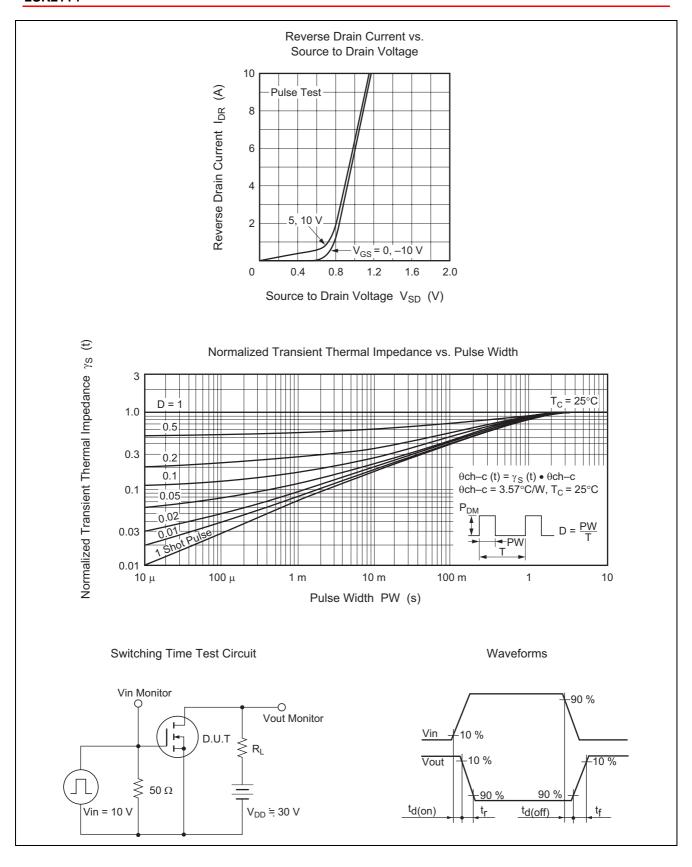
| Item                                       | Symbol               | Min | Тур  | Max | Unit | Test conditions  |
|--|----------------------|-----|------|-----|------|--|
| Drain to source breakdown voltage          | V <sub>(BR)DSS</sub> | 450 | _    | _   | V    | $I_D = 10 \text{ mA}, V_{GS} = 0$  |
| Gate to source breakdown voltage           | V <sub>(BR)GSS</sub> | ±30 | _    | _   | V    | $I_G = \pm 100 \ \mu A, \ V_{DS} = 0$  |
| Gate to source leak current                | I <sub>GSS</sub>     | _   | _    | ±10 | μΑ   | $V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$  |
| Zero gate voltage drain current            | I <sub>DSS</sub>     | _   | _    | 250 | μΑ   | V <sub>DS</sub> = 360 V, V <sub>GS</sub> = 0                                   |
| Gate to source cutoff voltage              | $V_{GS(off)}$        | 2.0 | _    | 3.0 | V    | $I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$                                    |
| Static drain to source on state resistance | R <sub>DS(on)</sub>  | _   | 1.0  | 1.4 | Ω    | $I_D = 2.5 \text{ A}, V_{GS} = 10 \text{ V}^{*3}$                              |
| Forward transfer admittance                | y <sub>fs</sub>      | 2.5 | 4.0  | _   | S    | $I_D = 2.5 \text{ A}, V_{DS} = 10 \text{ V}^{*3}$                              |
| Input capacitance                          | Ciss                 | _   | 640  | _   | pF   | $V_{DS} = 10 \text{ V}, V_{GS} = 0,$   |
| Output capacitance                         | Coss                 | _   | 160  | _   | pF   | f = 1 MHz  |
| Reverse transfer capacitance               | Crss                 | _   | 20   | _   | pF   |  |
| Turn-on delay time                         | t <sub>d(on)</sub>   | _   | 10   | _   | ns   | $I_D = 2.5 \text{ A}, V_{GS} = 10 \text{ V},$                                  |
| Rise time                                  | t <sub>r</sub>       | _   | 25   | _   | ns   | $R_L = 12 \Omega$  |
| Turn-off delay time                        | $t_{d(off)}$         | _   | 50   | _   | ns   |  |
| Fall time                                  | t <sub>f</sub>       | _   | 30   | _   | ns   |  |
| Body to drain diode forward voltage        | $V_{DF}$             | _   | 0.95 | _   | V    | $I_F = 5 \text{ A}, V_{GS} = 0$  |
| Body to drain diode reverse recovery time  | t <sub>rr</sub>      | _   | 300  | _   | ns   | $I_F = 5 \text{ A}, V_{GS} = 0,$<br>$di_F / dt = 100 \text{ A} / \mu \text{s}$ |

Note: 3. Pulse Test

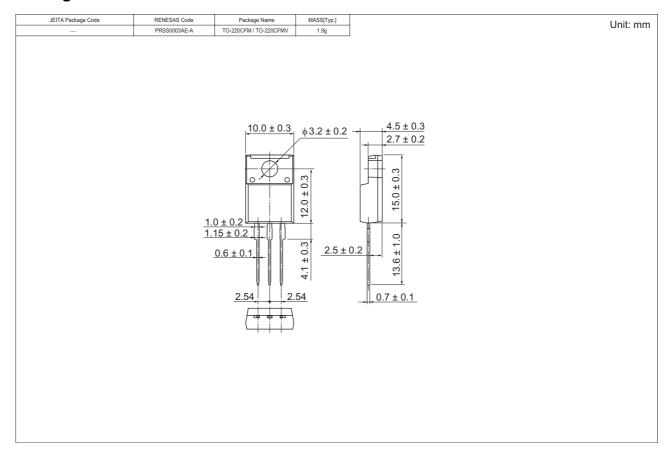
#### **Main Characteristics**







## **Package Dimensions**



### **Ordering Information**

| Part Name | Quantity | Shipping Container |
|-----------|----------|--------------------|
| 2SK2096-E | 30 pcs   | Plastic magazine   |

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